UP Storage SuperServer SSG-110P-NTR10

Key Applications

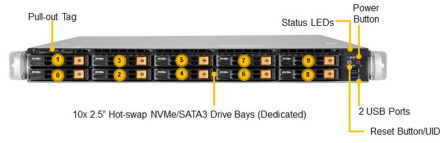Virtualization, Cloud Computing, All Flash Storage, CDN Optimized,

Key Features

- Single Socket P+ (LGA-4189) 3rd Gen Intel® Xeon® Scalable processors. Up to 270W TDP.;
- 8 DIMMs; Supports 3DS DDR4-3200: RDIMM/LRDIMM/Intel® DCPMM;
- 1 PCIe 4.0 x16 (FHHL) slot;
- Intel® Ethernet Controller X550 2x 10GbE RJ45;
- 10x Hot-swap 2.5'' All NVMe Gen 4 tool-less drive bays; Onboard 2x NVMe Gen 3/SATA M.2;
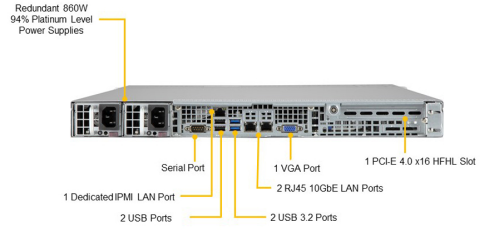- Redundant Platinum 860W Power Supply;

Form Factor	1U Rackmount Enclosure: 437 x 43 x 597mm (17.2" x 1.7" x 23.5") Package: 610 x 203 x 813mm (24" x 8" x 32")
Processor	Support Intel® 3rd Gen Xeon® Scalable Processors Single Socket LGA 4189 (Socket P+) supported TDP up to 270W;
System Memory	8 DIMM slots ECC RDIMM, DDR4-3200MHz ECC LRDIMM, DDR4-3200MHz Intel® DCPMM, DDR4-3200MHz
Drive Bays	10x 2.5" hot-swap NVMe drive bays;
Expansion Slots	1 PCIe 4.0 x16 FHHL slot(s)
On-Board Devices	NVMe: NVMe Gen 4 via MB onboard controller; RAID 0, 1, 5, 10 support (with additional VROC module) Chipset: Intel® C621A Network Connectivity: 2x 10GbE BaseT with Intel® X550 IPMI: Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support

Input / Output	LAN: 1 RJ45 Dedicated IPMI LAN port
	      2 RJ45 10GBase-T LAN ports
	USB: 5 USB 3.2 Gen 1 port(s) (2 front; 2 rear; 1 Type A)
	      4 USB 2.0 port(s) (2 rear; 2 headers)
	Video: 1 VGA port(s)
	Serial Port: 2 COM Port(s) (1 header; 1 rear)
	DOM: 2 SuperDOM (Disk on Module) port with built-in power

(Front View – System)

(Rear View – System)

Pull-out Tag

Status LEDs

Power Button

10x 2.5" Hot-swap NVMe/SATA3 Drive Bays (Dedicated)

2 USB Ports

Reset Button/UID

Redundant 860W 94% Platinum Level Power Supplies

Serial Port

1 Dedicated IPMI LAN Port

2 USB Ports

1 VGA Port

2 RJ45 10GbE LAN Ports

2 USB 3.2 Ports

1 PCI-E 4.0 x16 HFHL Slot

System Cooling	6x (4cm x 4cm x 5.6cm) heavy duty fan(s)
Power Supply	800W/860W 1U redundant power supply Dimension (W x H x L): 54.5 x 40.25 x 322 mm Output Type: Backplanes (gold finger)
System BIOS	BIOS Type: AMI 32MB SPI Flash EEPROM
Management	NMI; SUM; KVM with dedicated LAN; SPM; Intel® Node Manager; SSM; Redfish API; IPMI2.0
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory 　　7+1 Phase-switching voltage regulator module (VRM) FAN: Fans with tachometer monitoring 　　Status monitor for speed control 　　Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment 　　　　Thermal Control for fan connectors
Dimensions and Weight	Height: 1.7" (43 mm) Width: 17.2" (437 mm) Depth: 23.5" (597 mm) Gross Weight: 38 lbs (17.24 kg) Net Weight: 25 lbs (11.34 kg) Packaging: 8" (H) x 24" (W) x 32" (D) Available Color: Black
Operating Environment	Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -40°C to 70°C (-40°F to 158°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	Super X12SPO-NTF
Chassis	CSE-116TS-R860CBP-N10